



JIANGSU CHANGJIANG ELECTRONICS TECHNOLOGY CO., LTD

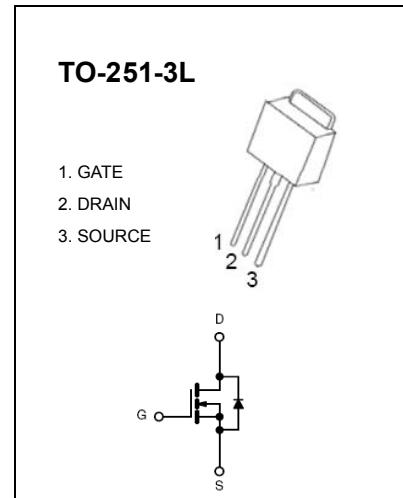
TO-251-3L Plastic-Encapsulate MOSFETs

CJD4410 N-Channel 30-V(D-S) MOSFET**FEATURE**

TrenchFET Power MOSFET

APPLICATIONS

- Load Switch
- Battery Switch

**Maximum ratings ($T_a=25^\circ\text{C}$ unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	7.5	A
Power Dissipation (note 1, $T_a=25^\circ\text{C}$)	P_D	1	W
Maximum Power Dissipation (note 2, $T_c=25^\circ\text{C}$)		15	
Thermal Resistance from Junction to Ambient ($t \leq 10\text{s}$)	$R_{\theta JA}$	125	$^\circ\text{C/W}$
Operating Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55 ~ +150	

Electrical characteristics ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	30			V
Gate-source threshold voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1		3	
Gate-source leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			± 100	nA
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Drain-source on-state resistance (note 3)	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$			13.5	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 5\text{A}$			20	
Forward transconductance (note 3)	g_{fs}	$V_{\text{DS}} = 15\text{V}, I_D = 5\text{A}$		8		S
Body diode voltage (note 3)	V_{SD}	$I_S = 2.3\text{A}, V_{\text{GS}} = 0$			1.1	V
Dynamic (note 4)						
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 25\text{V}, R_L = 25\Omega, I_D = 1\text{A}, V_{\text{GEN}} = 10\text{V}, R_G = 6\Omega$			15	ns
Rise time	t_r				15	
Turn-off delay time	$t_{\text{d}(\text{off})}$				60	
Fall time	t_f				25	
Gate Resistance	R_g	$f = 1\text{MHz}$	0.5		2.7	Ω

Notes :

1. This test is performed with no heat sink at $T_a=25^\circ\text{C}$.
2. This test is performed with infinite heat sink at $T_c=25^\circ\text{C}$.
3. Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production testing.